

Description

Features

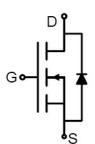
- 20V, 8A
 - $R_{DS(ON)}$ < 14m Ω @ V_{GS} =4.5V $R_{DS(ON)}$ < 22.5m Ω @ V_{GS} =2.5V
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead free product is acquired

Application

- Load Switch
- PWM Application
- Power management







Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM100N02A-S2	VSM100N02A	TAPING	SOT-23-3	7inch	3000	180000

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise specified)

Symbol	Parameter	Max.	Units	
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±12	V
I _D	Continuous Dunin Comment	T _A = 25℃	8	Α
	Continuous Drain Current	T _A = 100°C	5	Α
I_{DM}	Pulsed Drain Current note1		32	Α
P _D	Power Dissipation	T _A = 25°C	1.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Case		83.3	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	$^{\circ}$ C



Electrical Characteristics (TJ=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units		
Off Characteristic								
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	20	-	-	V		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V,	-	-	1.0	μA		
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA		
On Charac	On Characteristics							
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	0.5	0.75	1.2	V		
Б	Static Drain-Source on-Resistance	V _{GS} =4.5V, I _D =8A	-	11	14	mΩ		
R _{DS(on)}	note2	V _{GS} =2.5V, I _D =5A	-	16	22.5			
Dynamic C	Dynamic Characteristics							
C _{iss}	Input Capacitance	101111	-	1000	-	pF		
Coss	Output Capacitance	$V_{DS}=10V, V_{GS}=0V,$	-	182	-	pF		
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	164	-	pF		
Qg	Total Gate Charge	V _{DS} =10V, I _D =4A,	-	15	-	nC		
Q _{gs}	Gate-Source Charge		-	2	-	nC		
Q_{gd}	Gate-Drain("Miller") Charge	V _{GS} =4.5V	-	5.2	-	nC		
Switching	Characteristics							
t _{d(on)}	Turn-on Delay Time	101	-	9	-	ns		
t _r	Turn-on Rise Time	V _{DS} =10V,	-	25	-	ns		
t _{d(off)}	Turn-off Delay Time	$I_D=4A$, $R_{GEN}=3\Omega$,	-	37	-	ns		
t _f	Turn-off Fall Time	V _{GS} =4.5V	-	14	-	ns		
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings						
I.	Maximum Continuous Drain to Source Diode Forward Current				0	۸		
Is			-	-	8	Α		
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	32	Α		
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =8A	-	-	1.2	V		

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

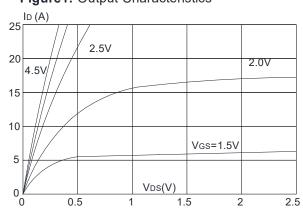


Figure 3:On-resistance vs. Drain Current

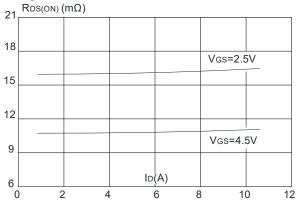


Figure 5: Gate Charge Characteristics

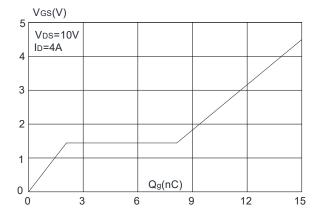


Figure 2: Typical Transfer Characteristics

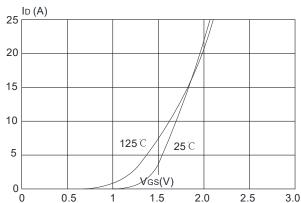


Figure 4: Body Diode Characteristics

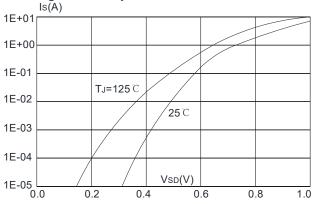


Figure 6: Capacitance Characteristics

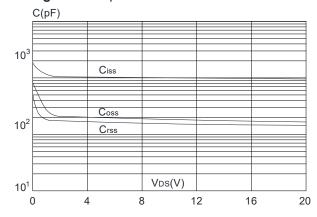




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

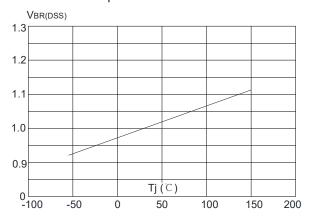


Figure 9: Maximum Safe Operating Area

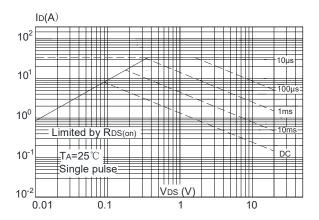


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

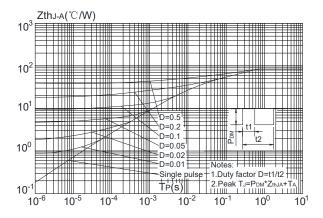


Figure 8: Normalized on Resistance vs. Junction Temperature

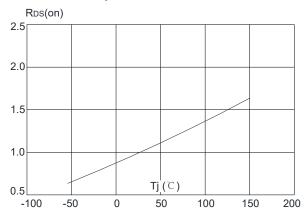
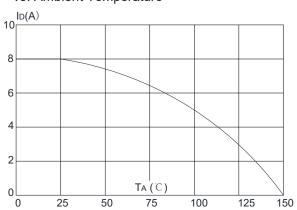


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature





Test Circuit

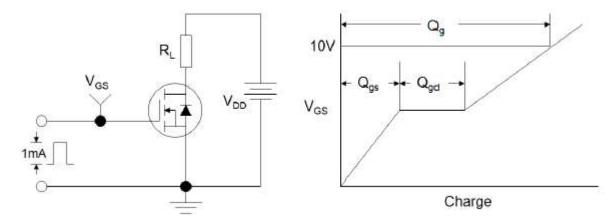


Figure1:Gate Charge Test Circuit & Waveform

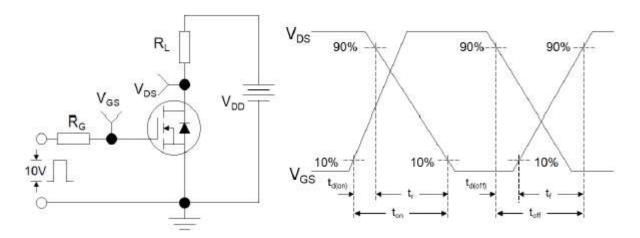


Figure 2: Resistive Switching Test Circuit & Waveforms

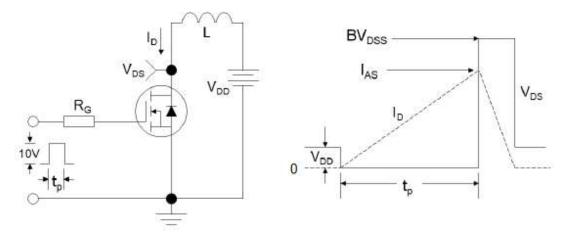


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms